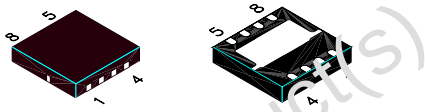
STL8NH3LL

N-channel 30 V, 0.012 Ω, 8 A - PowerFLAT™ (3.3x3.3) ultra low gate charge STripFET™ Power MOSFET

Features

Type	V_{DSS}	$R_{DS(on)}$	I_D
STL8NH3LL	30V	<0.015Ω	8A (1)

- Improved die-to-footprint ratio
- Very low profile package (1mm max)
- Very low thermal resistance
- Very low gate charge
- Low threshold device
- In compliance with the 2002/95/EC European directive



PowerFLAT™ (3.3x3.3)
(Chip Scale Package)

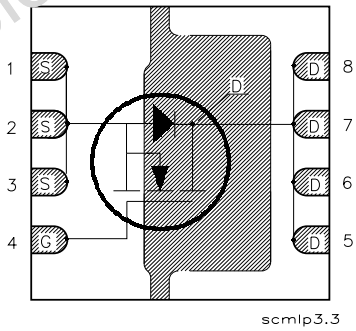
Description

This application specific Power MOSFET is the latest generation of STMicroelectronics unique STripFET™ technology. The resulting transistor is optimized for low on-resistance and minimal gate charge. The chip-scaled PowerFLAT™ package allows a significant board space saving, still boosting the performance.

Applications

- Switching application

Figure 1. Internal schematic diagram



TOP VIEW

Table 1. Device summary

Order code	Marking	Package	Packaging
STL8NH3LL	8NH3L	PowerFLAT™ (3.3x3.3)	Tape and reel

Contents

1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage (V_{GS} = 0)	30	V
V_{GS}	Gate-source voltage	± 18	V
I_D (1)	Drain current (continuous) at T_C = 25°C	8	A
I_D (1)	Drain current (continuous) at T_C=100°C	5	A
I_{DM} (2)	Drain current (pulsed)	32	A
P_{TOT} (3)	Total dissipation at T_C = 25°C	50	W
P_{TOT} (1)	Total dissipation at T_C = 25°C	2	W
	Derating factor	0.4	W/°C
T_J T_{stg}	Operating junction temperature Storage temperature	-55 to 150	°C

1. The value is rated according Rthj-pcb
2. Pulse width limited by safe operating area.
3. The vaule is rated according Rthj-c

Table 3. Thermal resistance

Symbol	Parameter	Value	Unit
$R_{thj\text{-}case}$	Thermal resistance junction-case (drain)	2.5	°C/W
$R_{thj\text{-}pcb}$ (1)	Thermal resistance junction-pcb	42.8	°C/W
$R_{thj\text{-}pcb}$ (2)	Thermal resistance junction-pcb	63.5	°C/W

1. When mounted on FR-4 board of 1inch², 2oz Cu, t < 10 sec
2. Steady state

2 Electrical characteristics

(T_{CASE}= 25 °C unless otherwise specified)

Table 4. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-Source breakdown voltage	I_D = 250 µA, V_{GS}= 0	30			V
I_{DSS}	Zero gate voltage drain current (V_{GS} = 0)	V_{DS} = max rating, V_{DS} = max rating @125°C			1 10	µA µA
I_{GSS}	Gate body leakage current (V_{DS} = 0)	V_{GS} = ±18 V			±100	nA
$V_{GS(th)}$	Gate threshold voltage	V_{DS}= V_{GS}, I_D = 250 µA	1		2.5	V
$R_{DS(on)}$	Static drain-source on resistance	V_{GS}= 10 V, I_D= 4 A V_{GS}= 4.5 V, I_D= 4 A		0.012 0.0135	0.015 0.017	Ω Ω

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
g_{fs} (1)	Forward transconductance	V_{DS} =15 V, I_D = 4 A		30		S
C_{iss} C_{oss} C_{rss}	Input capacitance Output capacitance Reverse transfer capacitance	V_{DS} =25 V, f=1 MHz, V_{GS}=0		965 285 38		pF pF pF
Q_g Q_{gs} Q_{gd}	Total gate charge Gate-source charge Gate-drain charge	V_{DD}=15 V, I_D = 8 A V_{GS} =4.5 V (see Figure 8)		9 3.7 3	12	nC nC nC
R_G	Gate input resistance	f=1 MHz gate DC bias = 0 test signal level = 20mV open drain	0.5	1.5	2.5	Ω

1. Pulsed: pulse duration= 300 µs, duty cycle 1.5%

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ t_r $t_{d(off)}$ t_f	Turn-on delay time Rise time Turn-off delay time Fall Time	V_{DD}=15 V, I_D= 4 A, R_G=4.7 Ω, V_{GS}=4.5 V (see Figure 14)	-	15 32 18 8.5	-	ns ns ns ns

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min	Typ.	Max	Unit
I_{SD}	Source-drain current		-		8	A
I_{SDM}(1)	Source-drain current (pulsed)		-		32	A
V_{SD}(2)	Forward on voltage	I_{SD}= 8 A, V_{GS}= 0	-		1.3	V
t_{rr} Q_{rr} I_{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	I_{SD}=8 A, di/dt = 100 A/µs, V_{DD}=20 V, Tj=150 °C (see Figure 16)	-	24 17.4 1.45		ns nC A

1. Pulse width limited by safe operating area
2. Pulsed: pulse duration= 300 µs, duty cycle 1.5 %

2.1 Electrical characteristics (curves)

Figure 2. Safe operating area

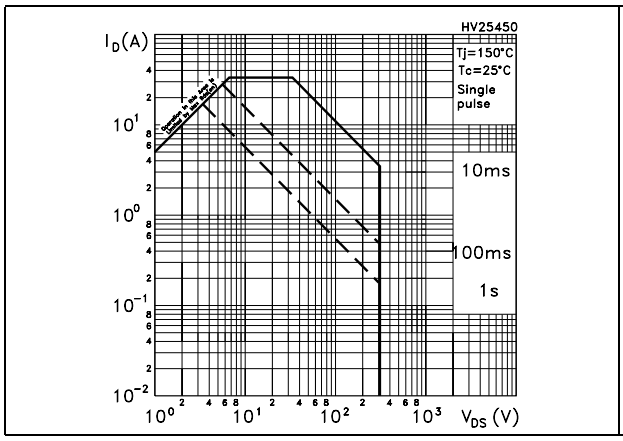


Figure 3. Thermal impedance

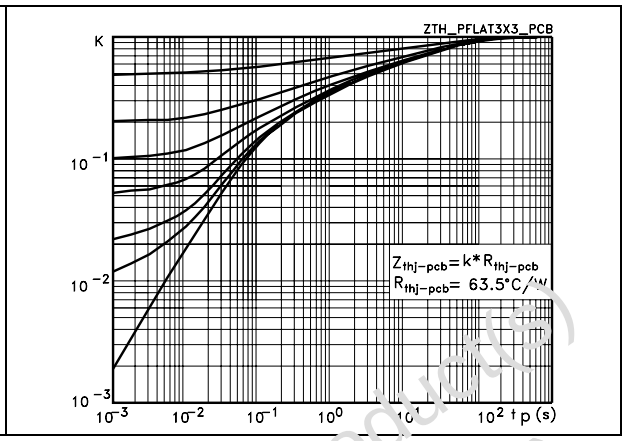


Figure 4. Output characteristics

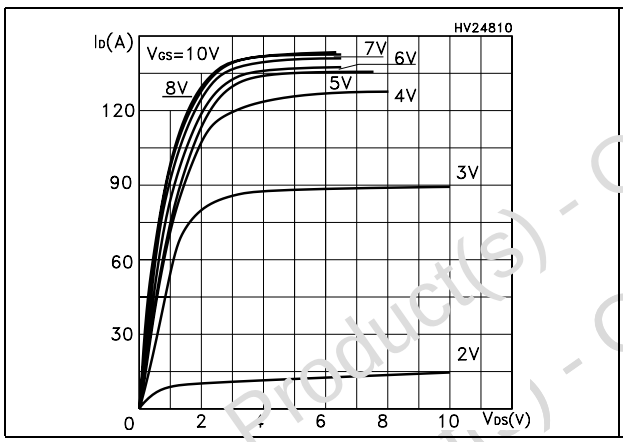


Figure 5. Transfer characteristics

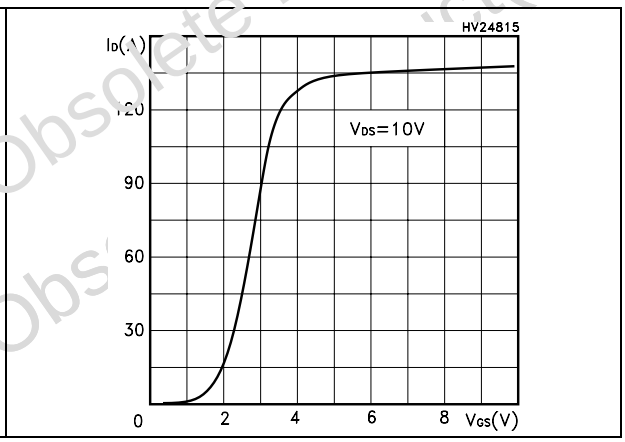


Figure 6. Transconductance

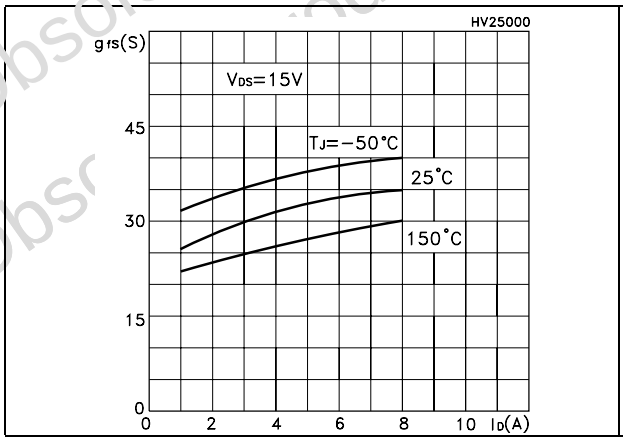


Figure 7. Static drain-source on resistance

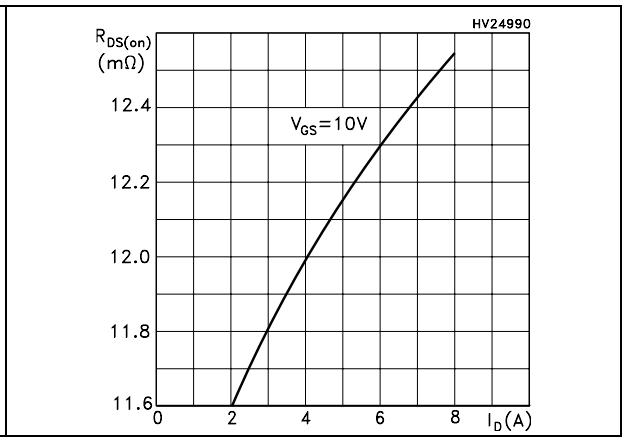


Figure 8. Gate charge vs gate-source voltage

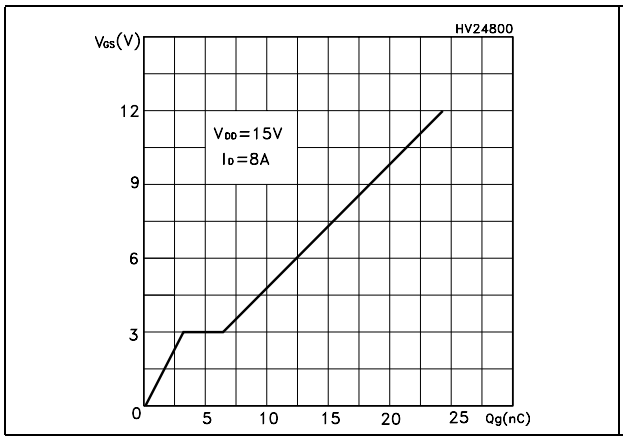


Figure 9. Capacitance variations

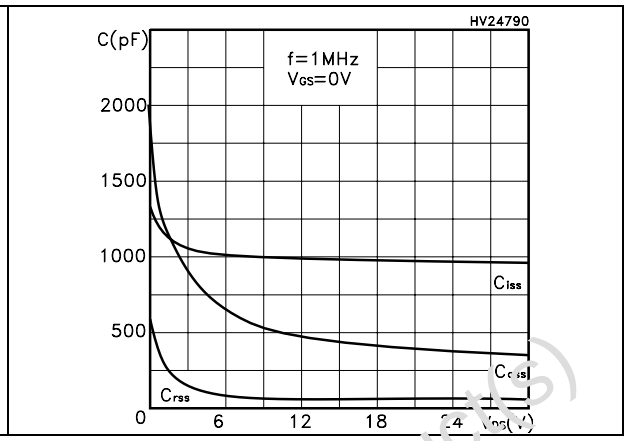


Figure 10. Normalized gate threshold voltage vs temperature

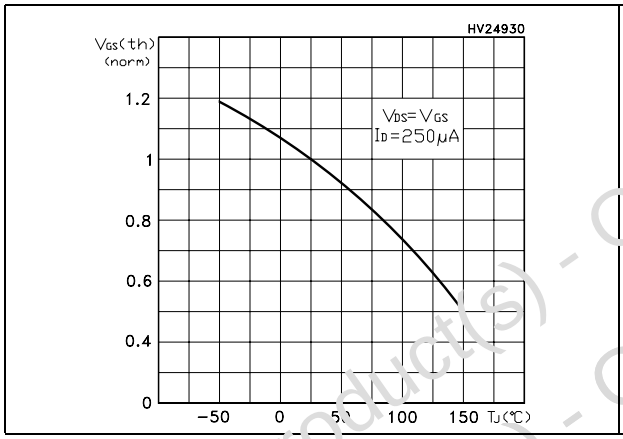


Figure 11. Normalized on resistance vs temperature

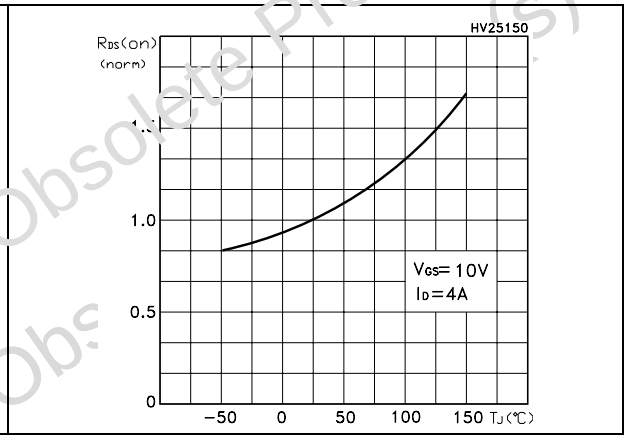


Figure 12. Source-drain diode forward characteristics

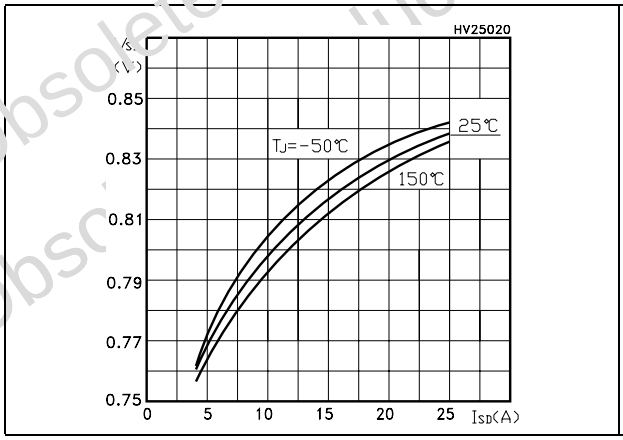
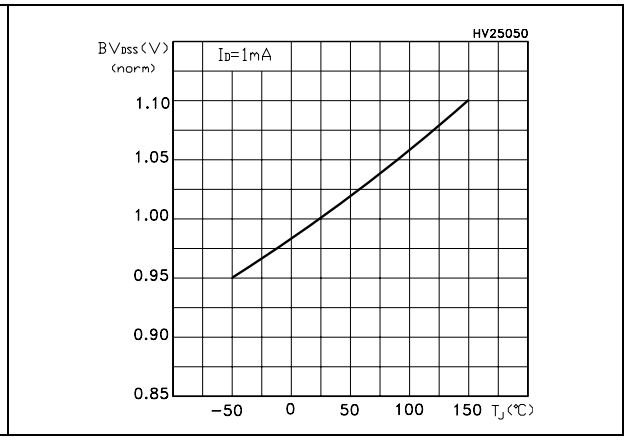


Figure 13. Normalized B_{VDSS} vs temperature



3 Test circuits

Figure 14. Switching times test circuit for resistive load

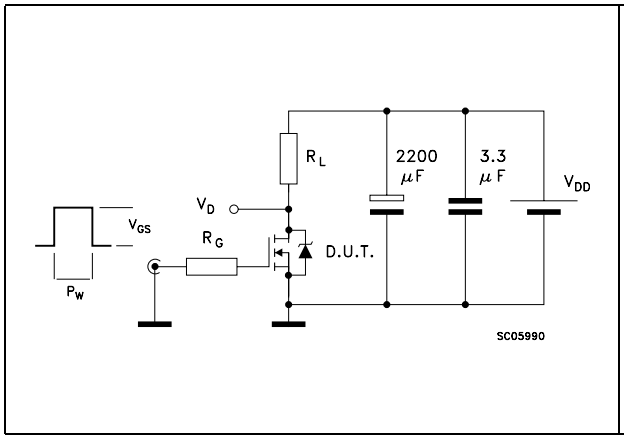


Figure 15. Gate charge test circuit

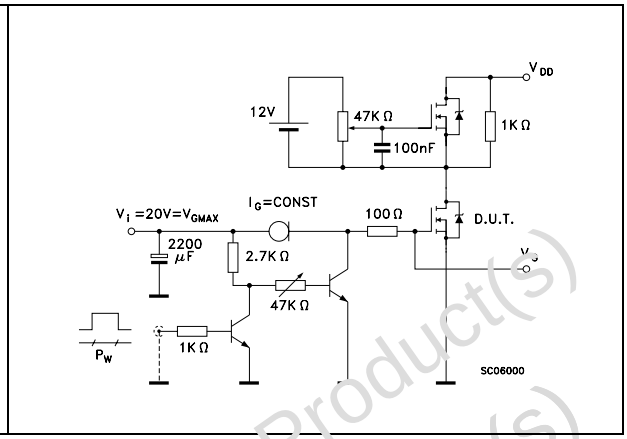


Figure 16. Inductive load switching and diode recovery times

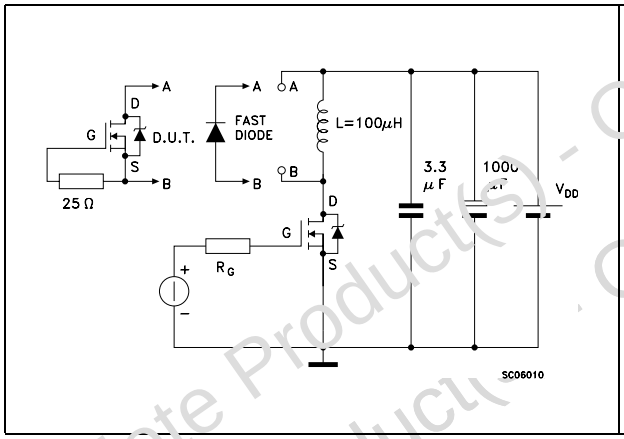


Figure 17. Unclamped inductive load test circuit

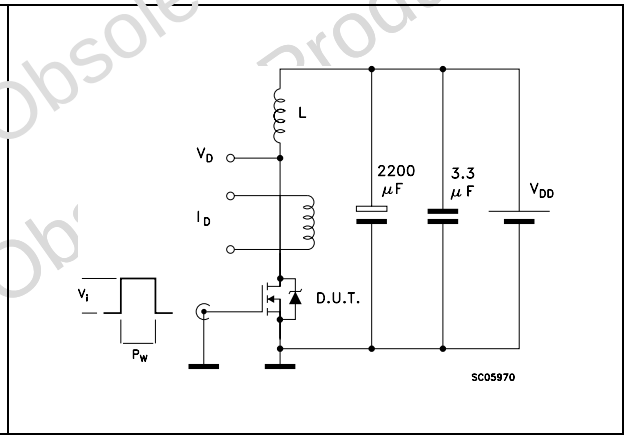


Figure 18. Unclamped inductive waveform

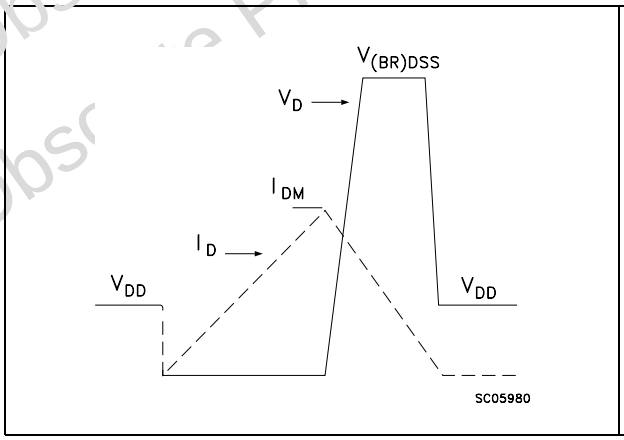
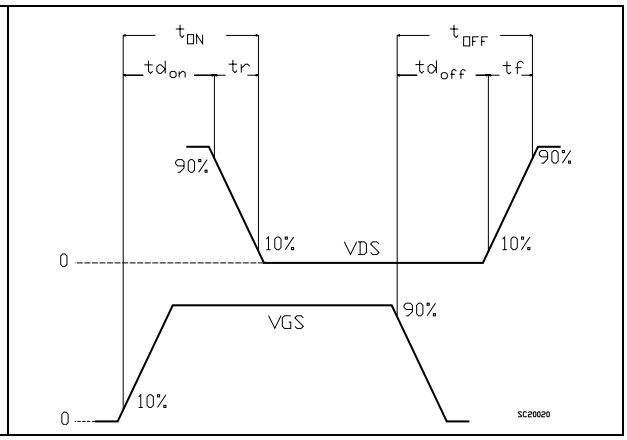


Figure 19. Switching time waveform



4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

Table 8. Package dimensions

Dim.	mm.			inch		
	Min.	Typ	Max.	Min.	Typ.	Max.
A	0.80	0.90	1.00	0.031	0.035	0.039
A1		0.02	0.05		0.0007	0.0019
A3		0.20			0.007	
b	0.23	0.30	0.38	0.009	0.011	0.015
C		0.328			0.012	
C1		0.12			0.004	
D		3.30			0.13	
D2	2.50	2.65	2.75	0.098	0.104	0.108
E		3.30			0.13	
E2	1.25	1.40	1.50	0.049	0.055	0.059
F		1.325			0.052	
F1		0.975			0.038	
e		0.65			0.025	
L	0.30		0.50	0.011		0.019

Figure 20. Package drawing

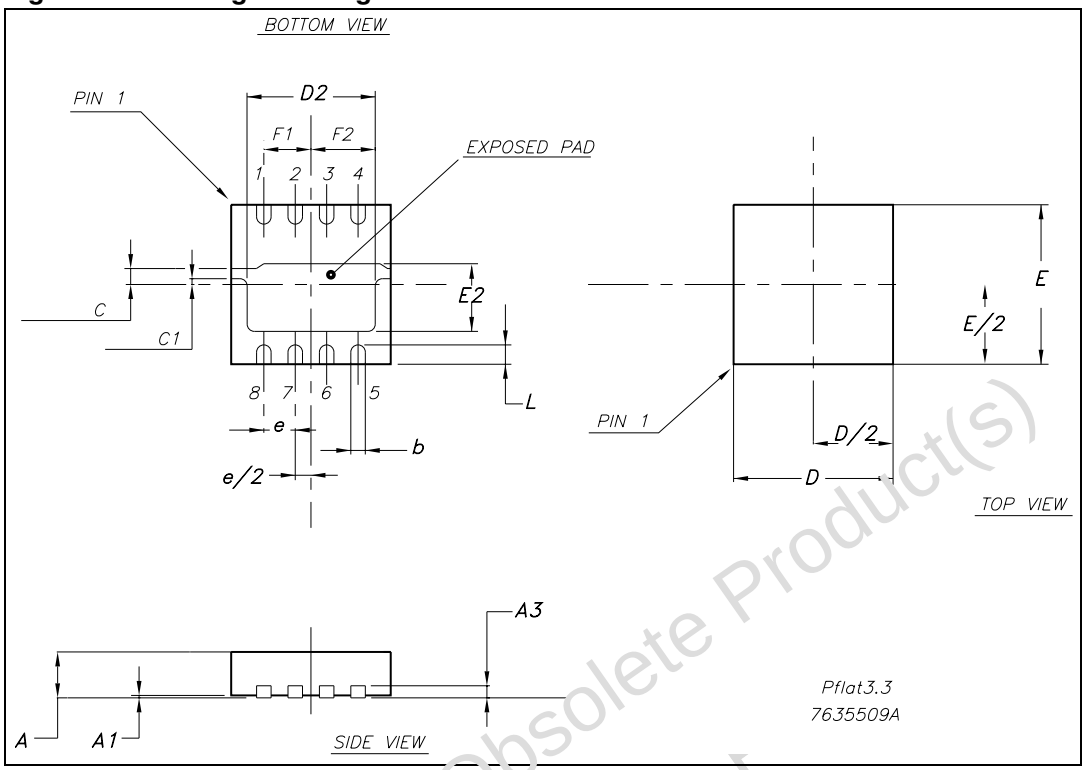
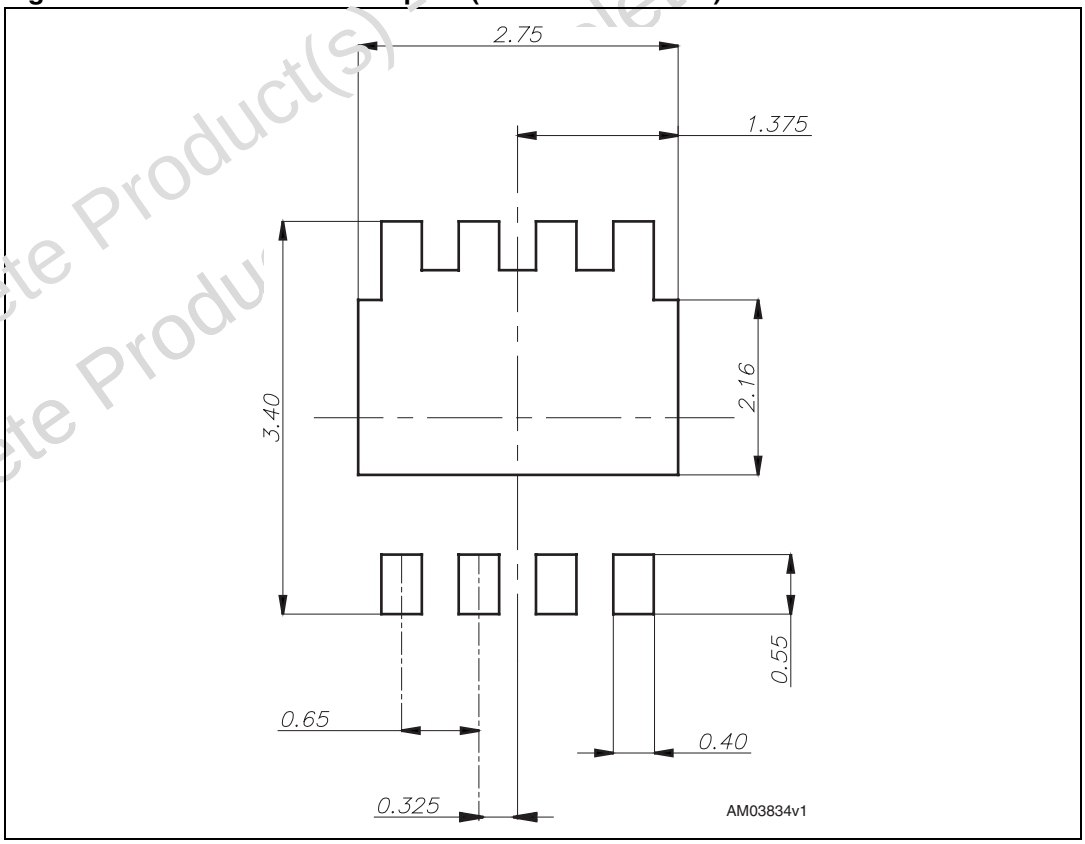


Figure 21. Recommended footprint (dimensions in mm)



5 Revision history

Table 9. Document revision history

Date	Revision	Changes
21-Jul-2004	1	First release
05-Oct-2004	2	Values changed
19-Oct-2004	3	New value inserted
22-Nov-2004	4	Document updated
21-Feb-2005	5	Final version
18-Apr-2005	6	Modified *Figure 4*, *Figure 6.*, *Figure 9.*,*Figure 10.*
14-Mar-2006	7	New template
10-Sep-2009	8	Inserted *Figure 21*

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